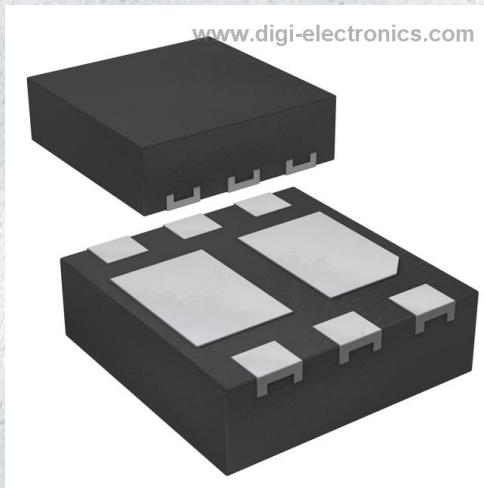


# PMDPB70XPE,115 Datasheet



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|                              |  |
|------------------------------|--|
| DiGi Electronics Part Number | PMDPB70XPE,115-DG                                      |
| Manufacturer                 | <a href="#">Nexperia USA Inc.</a>                      |
| Manufacturer Product Number  | PMDPB70XPE,115   |
| Description                  | MOSFET 2P-CH 20V 3A 6HUSON                             |
| Detailed Description         | Mosfet Array 20V 3A 515mW Surface Mount 6-HUSO N (2x2) |



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## Purchase and inquiry

**Manufacturer Product Number:**

PMDPB70XPE,115

**Series:**

-

**Technology:**

MOSFET (Metal Oxide)

**FET Feature:**

Logic Level Gate

**Current - Continuous Drain (Id) @ 25°C:**

3A

**Vgs(th) (Max) @ Id:**

1.25V @ 250µA

**Input Capacitance (Ciss) (Max) @ Vds:**

600pF @ 10V

**Operating Temperature:**

-55°C ~ 150°C (TJ)

**Package / Case:**

6-UFDN Exposed Pad

**Base Product Number:**

PMDPB70

**Manufacturer:**

Nexperia USA Inc.

**Product Status:**

Active

**Configuration:**

2 P-Channel (Dual)

**Drain to Source Voltage (Vdss):**

20V

**Rds On (Max) @ Id, Vgs:**

79mOhm @ 2A, 4.5V

**Gate Charge (Qg) (Max) @ Vgs:**

7.5nC @ 4.5V

**Power - Max:**

515mW

**Mounting Type:**

Surface Mount

**Supplier Device Package:**

6-HUSON (2x2)

## Environmental & Export classification

**RoHS Status:**

ROHS3 Compliant

**REACH Status:**

REACH Unaffected

**HTSUS:**

8541.21.0095

**Moisture Sensitivity Level (MSL):**

1 (Unlimited)

**ECCN:**

EAR99



# PMDPB70XPE

## 20 V dual P-channel Trench MOSFET

Rev. 1 — 20 June 2012

Product data sheet

## 1. Product profile

### 1.1 General description

Dual small-signal P-channel enhancement mode Field-Effect Transistor (FET) in a leadless medium power DFN2020-6 (SOT1118) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

### 1.2 Features and benefits

- Very fast switching
- Trench MOSFET technology
- 2 kV ElectroStatic Discharge (ESD) protection

### 1.3 Applications

- Relay driver
- High-speed line driver
- High-side load switch
- Switching circuits

### 1.4 Quick reference data

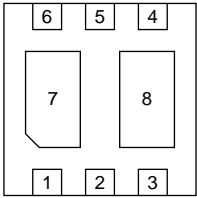
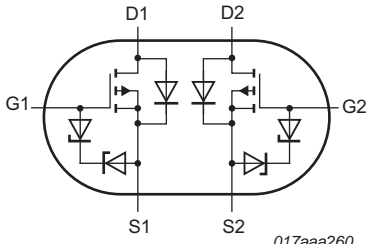
Table 1. Quick reference data

| Symbol   | Parameter                        | Conditions  | Min | Typ | Max  | Unit |
|--|----------------------------------|---|-----|-----|------|------|
| <b>Per transistor</b>                          |                                  |   |     |     |      |      |
| $V_{DS}$                                       | drain-source voltage             | $T_j = 25\text{ °C}$  | -   | -   | -20  | V    |
| $V_{GS}$                                       | gate-source voltage              |   | -12 | -   | 12   | V    |
| $I_D$  | drain current                    | $V_{GS} = -4.5\text{ V}$ ; $T_{amb} = 25\text{ °C}$ ; $t \leq 5\text{ s}$ | [1] | -   | -4.2 | A    |
| <b>Static characteristics (per transistor)</b> |                                  |   |     |     |      |      |
| $R_{DS(on)}$                                   | drain-source on-state resistance | $V_{GS} = -4.5\text{ V}$ ; $I_D = -2\text{ A}$ ; $T_j = 25\text{ °C}$     | -   | 66  | 79   | mΩ   |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm<sup>2</sup>.

## 2. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline  | Graphic symbol   |
|-----|--------|-------------|---|--|
| 1   | S1     | source TR1  |  <p>Transparent top view</p> <p><b>DFN2020-6 (SOT1118)</b></p> |  <p>017aaa260</p> |
| 2   | G1     | gate TR1    |   |  |
| 3   | D2     | drain TR2   |   |  |
| 4   | S2     | source TR2  |   |  |
| 5   | G2     | gate TR2    |   |  |
| 6   | D1     | drain TR1   |   |  |
| 7   | D1     | drain TR1   |   |  |
| 8   | D2     | drain TR2   |   |  |

## 3. Ordering information

Table 3. Ordering information

| Type number | Package   |  |         |
|-------------|-----------|--|---------|
|             | Name      | Description  | Version |
| PMDPB70XPE  | DFN2020-6 | plastic thermal enhanced ultra thin small outline package; no leads; 6 terminals | SOT1118 |

## 4. Marking

Table 4. Marking codes

| Type number | Marking code |
|-------------|--------------|
| PMDPB70XPE  | 2B           |

## 5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

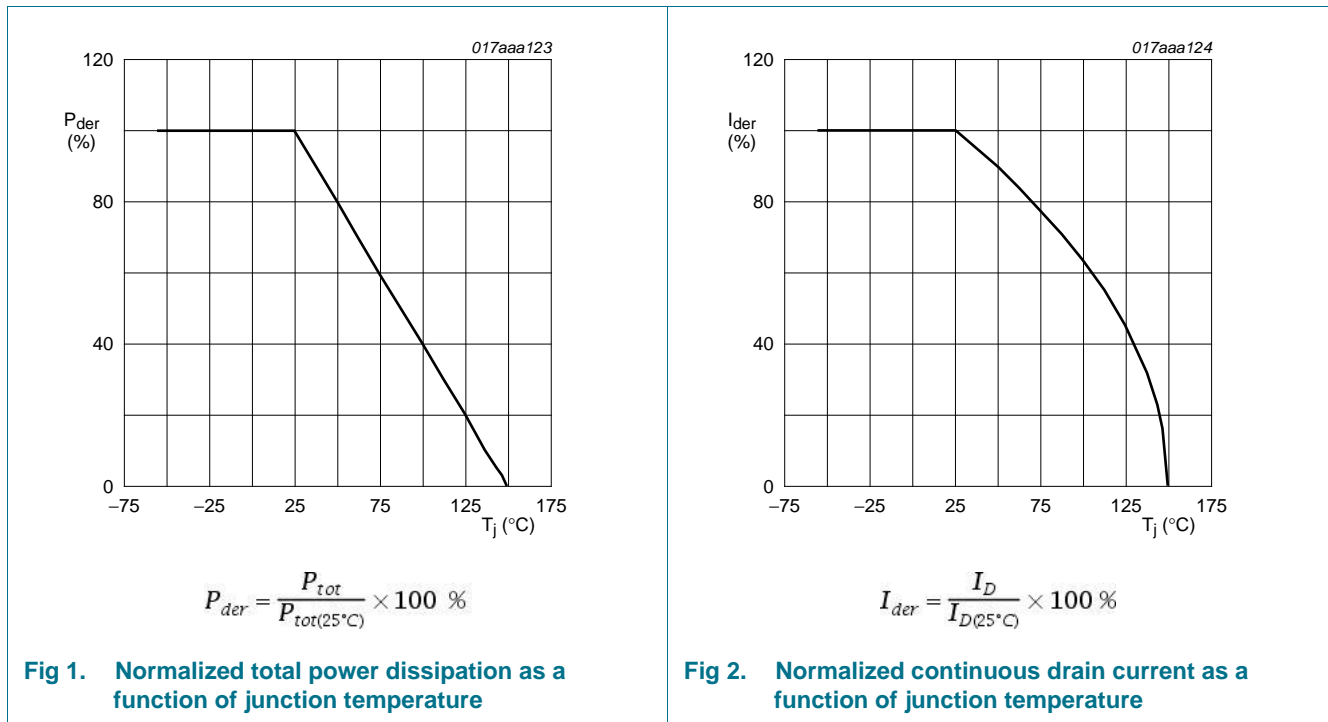
| Symbol                    | Parameter               | Conditions   | Min | Max | Unit |    |
|---------------------------|-------------------------|--|-----|-----|------|----|
| <b>Per transistor</b>     |                         |  |     |     |      |    |
| $V_{DS}$                  | drain-source voltage    | $T_j = 25\text{ °C}$   | -   | -20 | V    |    |
| $V_{GS}$                  | gate-source voltage     |  | -12 | 12  | V    |    |
| $I_D$                     | drain current           | $V_{GS} = -4.5\text{ V}; T_{amb} = 25\text{ °C}; t \leq 5\text{ s}$      | [1] | -   | -4.2 | A  |
|                           |                         | $V_{GS} = -4.5\text{ V}; T_{amb} = 25\text{ °C}$                         | [1] | -   | -3   | A  |
|                           |                         | $V_{GS} = -4.5\text{ V}; T_{amb} = 100\text{ °C}$                        | [1] | -   | -2.1 | A  |
| $I_{DM}$                  | peak drain current      | $T_{amb} = 25\text{ °C};$ single pulse; $t_p \leq 10\text{ }\mu\text{s}$ | -   | -12 | A    |    |
| $P_{tot}$                 | total power dissipation | $T_{amb} = 25\text{ °C}$   | [2] | -   | 515  | mW |
|                           |                         |  | [1] | -   | 1210 | mW |
|                           |                         | $T_{sp} = 25\text{ °C}$  |     | -   | 8330 | mW |
| <b>Source-drain diode</b> |                         |  |     |     |      |    |
| $I_S$                     | source current          | $T_{amb} = 25\text{ °C}$   | [1] | -   | -1.3 | A  |

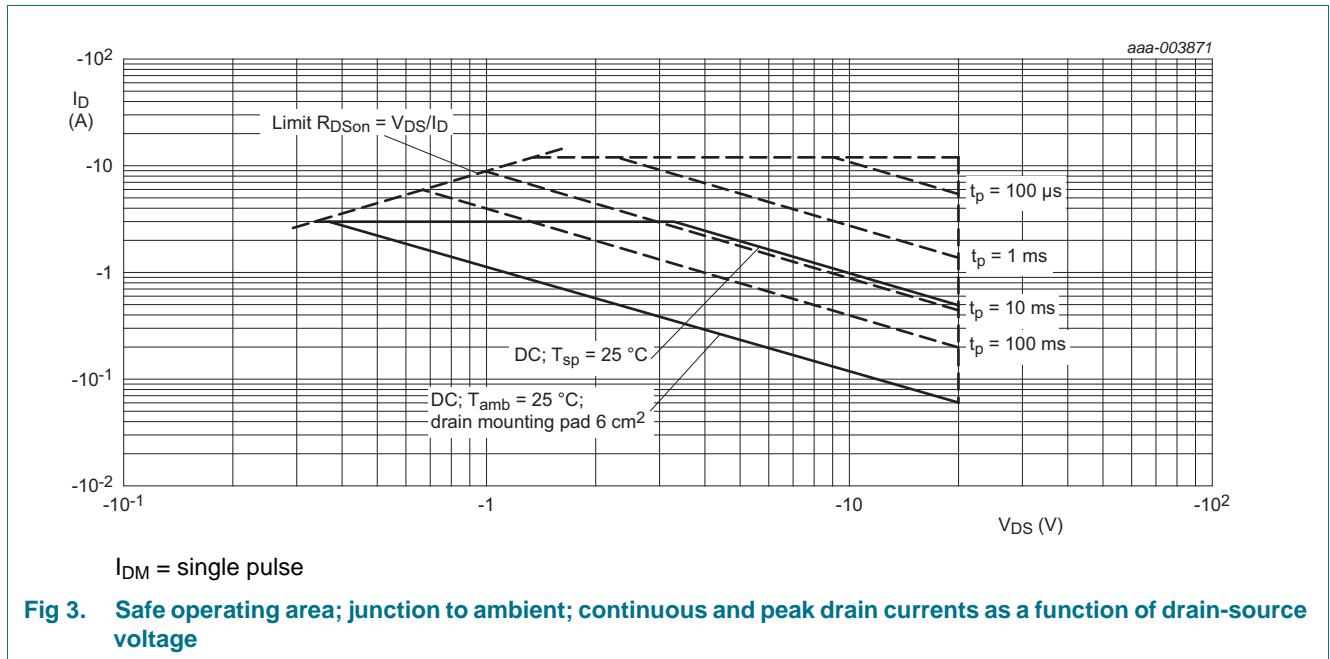
**Table 5. Limiting values ...continued**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol                    | Parameter                       | Conditions                  | Min | Max | Unit   |
|---------------------------|---------------------------------|-----------------------------|-----|-----|--------|
| <b>ESD maximum rating</b> |                                 |                             |     |     |        |
| V <sub>ESD</sub>          | electrostatic discharge voltage | HBM; C = 100 pF; R = 1.5 kΩ | [3] | -   | 2000 V |
| <b>Per device</b>         |                                 |                             |     |     |        |
| T <sub>j</sub>            | junction temperature            |                             | -55 | 150 | °C     |
| T <sub>amb</sub>          | ambient temperature             |                             | -55 | 150 | °C     |
| T <sub>stg</sub>          | storage temperature             |                             | -65 | 150 | °C     |

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm<sup>2</sup>.
- [2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.
- [3] Measured between all pins.





**Fig 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage**

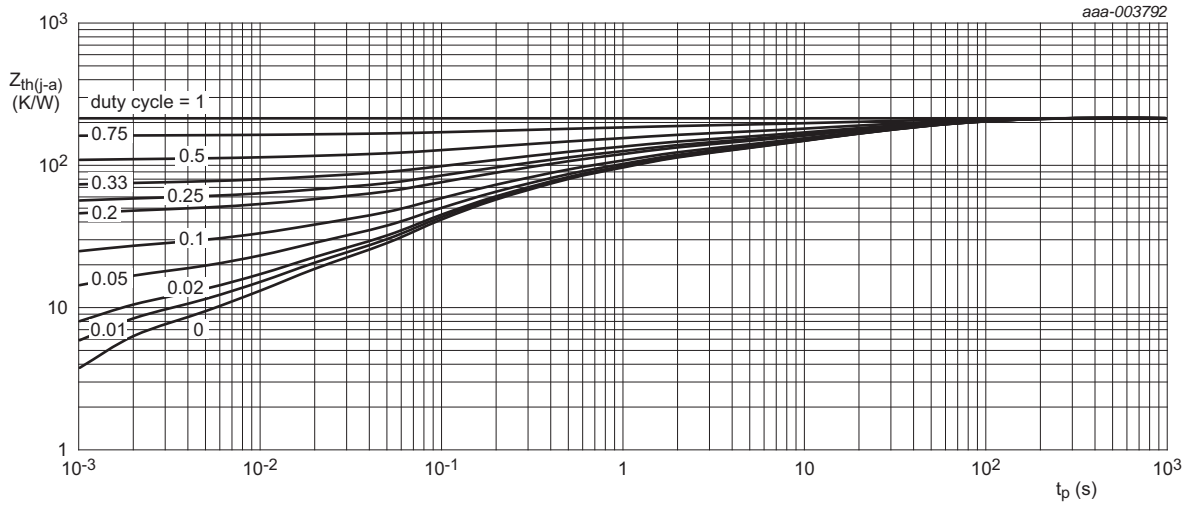
## 6. Thermal characteristics

**Table 6. Thermal characteristics**

| Symbol                | Parameter  | Conditions                        | Min | Typ | Max | Unit |     |
|-----------------------|--|-----------------------------------|-----|-----|-----|------|-----|
| <b>Per transistor</b> |  |                                   |     |     |     |      |     |
| $R_{th(j-a)}$         | thermal resistance from junction to ambient      | in free air                       | [1] | -   | 212 | 244  | K/W |
|                       |  |                                   | [2] | -   | 90  | 104  | K/W |
|                       |  | in free air; $t \leq 5 \text{ s}$ | [2] | -   | 55  | 64   | K/W |
| $R_{th(j-sp)}$        | thermal resistance from junction to solder point |                                   | -   | 11  | 15  | K/W  |     |

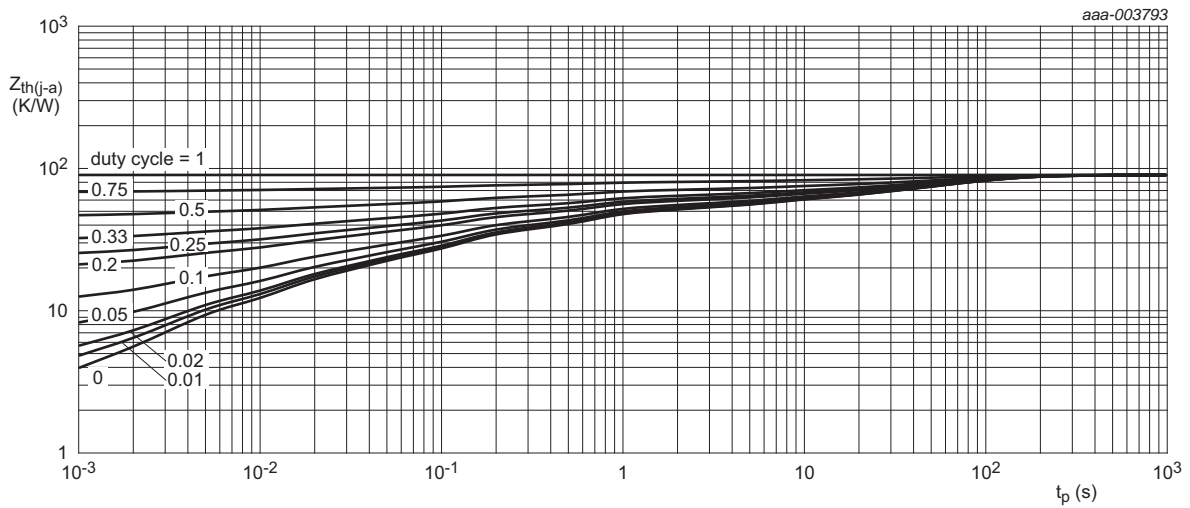
[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain  $6 \text{ cm}^2$ .



FR4 PCB, standard footprint

**Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**



FR4 PCB, mounting pad for drain 6 cm<sup>2</sup>

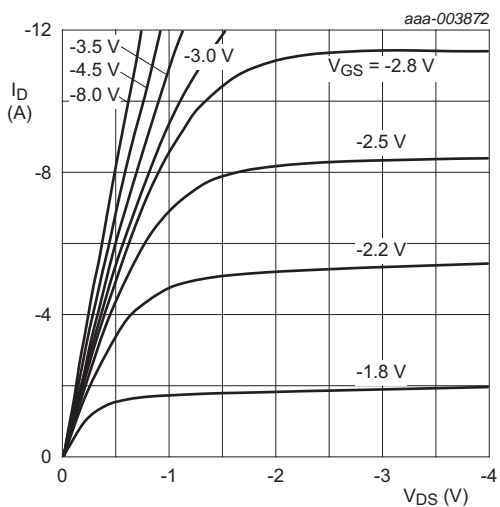
**Fig 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**

## 7. Characteristics

Table 7. Characteristics

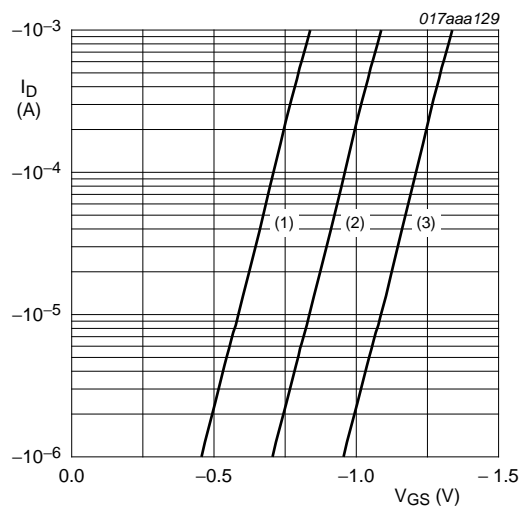
| Symbol  | Parameter                        | Conditions   | Min   | Typ  | Max   | Unit             |
|---|----------------------------------|--|-------|------|-------|------------------|
| <b>Static characteristics (per transistor)</b>  |                                  |  |       |      |       |                  |
| $V_{(BR)DSS}$                                   | drain-source breakdown voltage   | $I_D = -250 \mu\text{A}$ ; $V_{GS} = 0 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$  | -20   | -    | -     | V                |
| $V_{GSth}$                                      | gate-source threshold voltage    | $I_D = -250 \mu\text{A}$ ; $V_{DS} = V_{GS}$ ; $T_j = 25 \text{ }^\circ\text{C}$   | -0.75 | -1   | -1.25 | V                |
| $I_{DSS}$                                       | drain leakage current            | $V_{DS} = -20 \text{ V}$ ; $V_{GS} = 0 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$  | -     | -    | -1    | $\mu\text{A}$    |
|   |                                  | $V_{DS} = -20 \text{ V}$ ; $V_{GS} = 0 \text{ V}$ ; $T_j = 150 \text{ }^\circ\text{C}$   | -     | -    | -10   | $\mu\text{A}$    |
| $I_{GSS}$                                       | gate leakage current             | $V_{GS} = 12 \text{ V}$ ; $V_{DS} = 0 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$   | -     | -    | 10    | $\mu\text{A}$    |
|   |                                  | $V_{GS} = -12 \text{ V}$ ; $V_{DS} = 0 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$  | -     | -    | -10   | $\mu\text{A}$    |
| $R_{DSon}$                                      | drain-source on-state resistance | $V_{GS} = -4.5 \text{ V}$ ; $I_D = -2 \text{ A}$ ; $T_j = 25 \text{ }^\circ\text{C}$   | -     | 66   | 79    | $\text{m}\Omega$ |
|   |                                  | $V_{GS} = -4.5 \text{ V}$ ; $I_D = -2 \text{ A}$ ; $T_j = 150 \text{ }^\circ\text{C}$  | -     | 94   | 112   | $\text{m}\Omega$ |
|   |                                  | $V_{GS} = -2.5 \text{ V}$ ; $I_D = -1.5 \text{ A}$ ; $T_j = 25 \text{ }^\circ\text{C}$   | -     | 98   | 123   | $\text{m}\Omega$ |
| $g_{fs}$  | forward transconductance         | $V_{DS} = -10 \text{ V}$ ; $I_D = -2 \text{ A}$ ; $T_j = 25 \text{ }^\circ\text{C}$  | -     | 7.3  | -     | S                |
| <b>Dynamic characteristics (per transistor)</b> |                                  |  |       |      |       |                  |
| $Q_{G(tot)}$                                    | total gate charge                | $V_{DS} = -10 \text{ V}$ ; $I_D = -2 \text{ A}$ ; $V_{GS} = -4.5 \text{ V}$ ;<br>$T_j = 25 \text{ }^\circ\text{C}$                           | -     | 5    | 7.5   | nC               |
| $Q_{GS}$  | gate-source charge               |  | -     | 1.1  | -     | nC               |
| $Q_{GD}$  | gate-drain charge                |  | -     | 1.1  | -     | nC               |
| $C_{iss}$                                       | input capacitance                | $V_{DS} = -10 \text{ V}$ ; $f = 1 \text{ MHz}$ ; $V_{GS} = 0 \text{ V}$ ;<br>$T_j = 25 \text{ }^\circ\text{C}$                               | -     | 600  | -     | pF               |
| $C_{oss}$                                       | output capacitance               |  | -     | 103  | -     | pF               |
| $C_{rss}$                                       | reverse transfer capacitance     |  | -     | 77   | -     | pF               |
| $t_{d(on)}$                                     | turn-on delay time               | $V_{DS} = -10 \text{ V}$ ; $I_D = -2 \text{ A}$ ; $V_{GS} = -4.5 \text{ V}$ ;<br>$R_{G(ext)} = 6 \Omega$ ; $T_j = 25 \text{ }^\circ\text{C}$ | -     | 7    | -     | ns               |
| $t_r$   | rise time                        |  | -     | 16   | -     | ns               |
| $t_{d(off)}$                                    | turn-off delay time              |  | -     | 33   | -     | ns               |
| $t_f$   | fall time                        |  | -     | 15   | -     | ns               |
| <b>Source-drain diode (per transistor)</b>      |                                  |  |       |      |       |                  |
| $V_{SD}$  | source-drain voltage             | $I_S = -0.5 \text{ A}$ ; $V_{GS} = 0 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$  | -     | -0.7 | -1.2  | V                |





$T_j = 25\text{ }^\circ\text{C}$

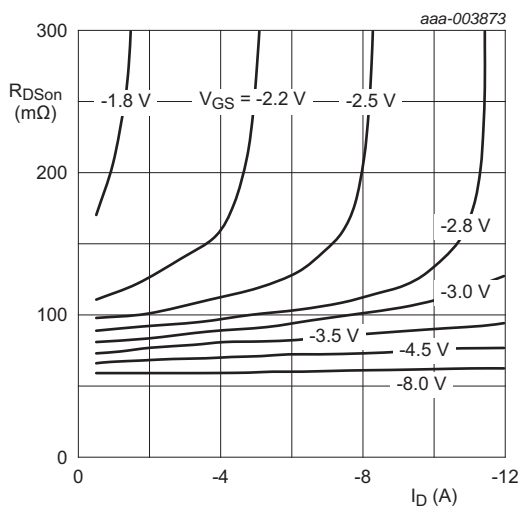
**Fig 6. Output characteristics: drain current as a function of drain-source voltage; typical values**



$T_j = 25\text{ }^\circ\text{C}; V_{DS} = -3\text{ V}$

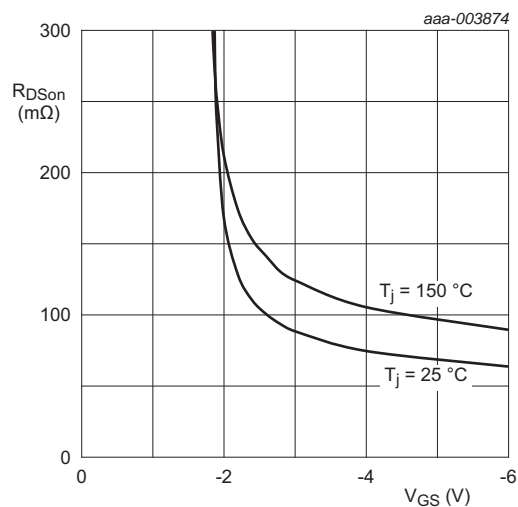
- (1) minimum values
- (2) typical values
- (3) maximum values

**Fig 7. Sub-threshold drain current as a function of gate-source voltage**



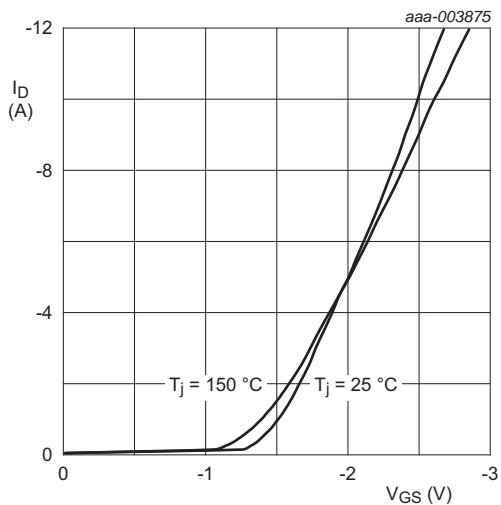
$T_j = 25\text{ }^\circ\text{C}$

**Fig 8. Drain-source on-state resistance as a function of drain current; typical values**



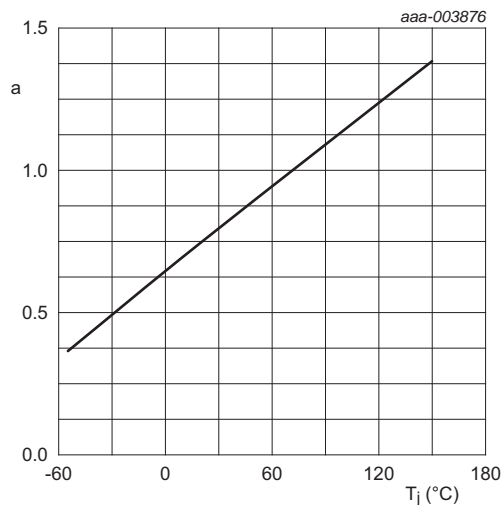
$I_D = -2\text{ A}$

**Fig 9. Drain-source on-state resistance as a function of gate-source voltage; typical values**



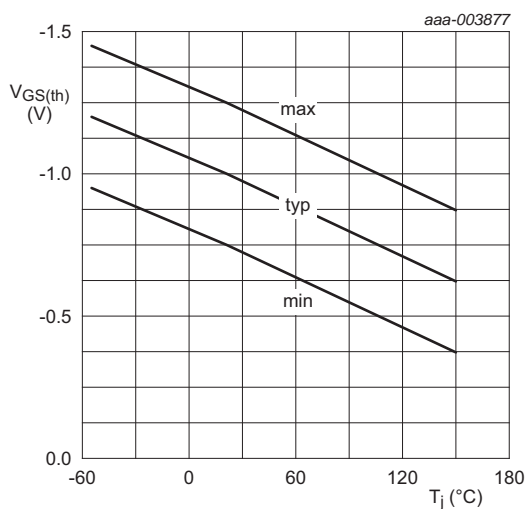
$$V_{DS} > I_D \times R_{DS(on)}$$

Fig 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values



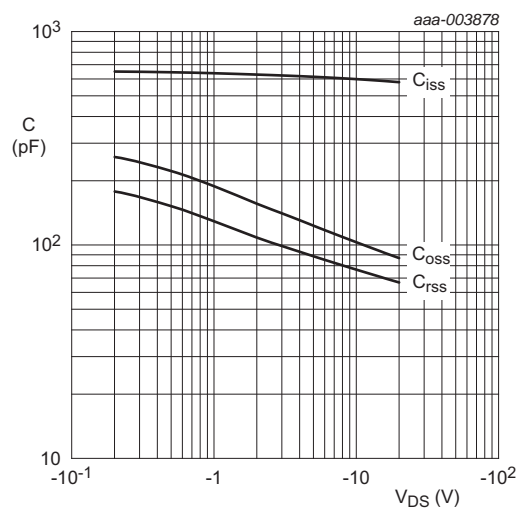
$$a = \frac{R_{DS(on)}}{R_{DS(on)(25^\circ C)}}$$

Fig 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values



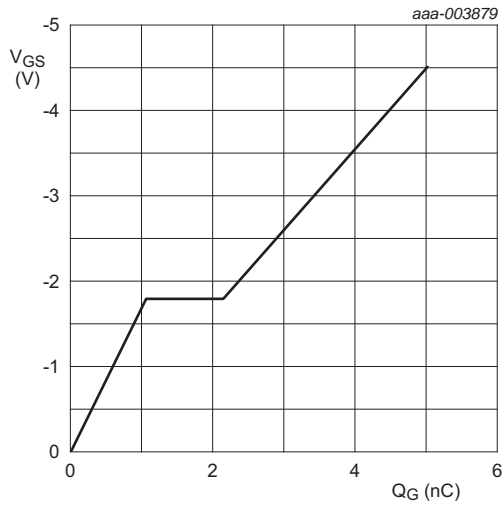
$$I_D = -0.25 \text{ mA}; V_{DS} = V_{GS}$$

Fig 12. Gate-source threshold voltage as a function of junction temperature



$$f = 1 \text{ MHz}; V_{GS} = 0 \text{ V}$$

Fig 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$I_D = -2 \text{ A}; V_{DS} = -10 \text{ V}; T_{amb} = 25 \text{ }^\circ\text{C}$

Fig 14. Gate-source voltage as a function of gate charge; typical values

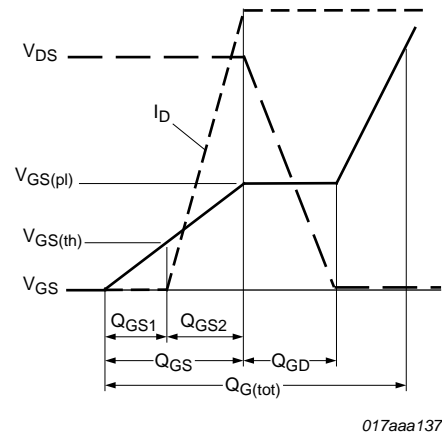
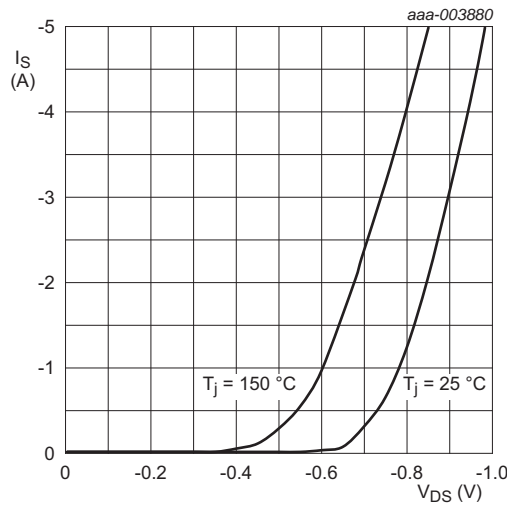


Fig 15. Gate charge waveform definitions



$V_{GS} = 0 \text{ V}$

Fig 16. Source current as a function of source-drain voltage; typical values

## 8. Test information

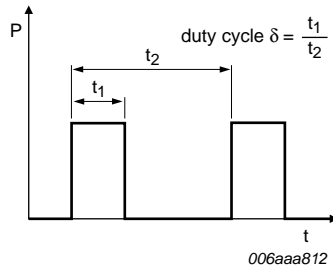


Fig 17. Duty cycle definition

## 9. Package outline

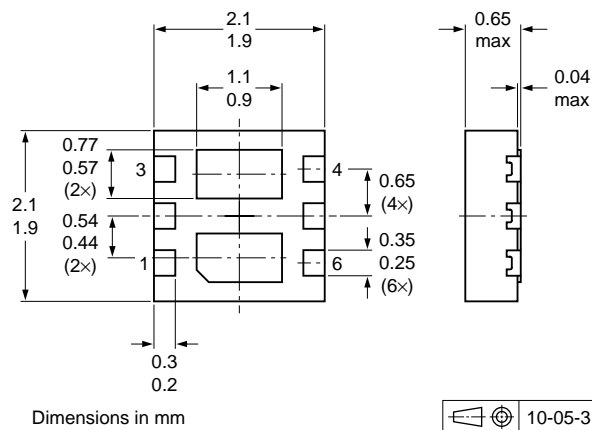
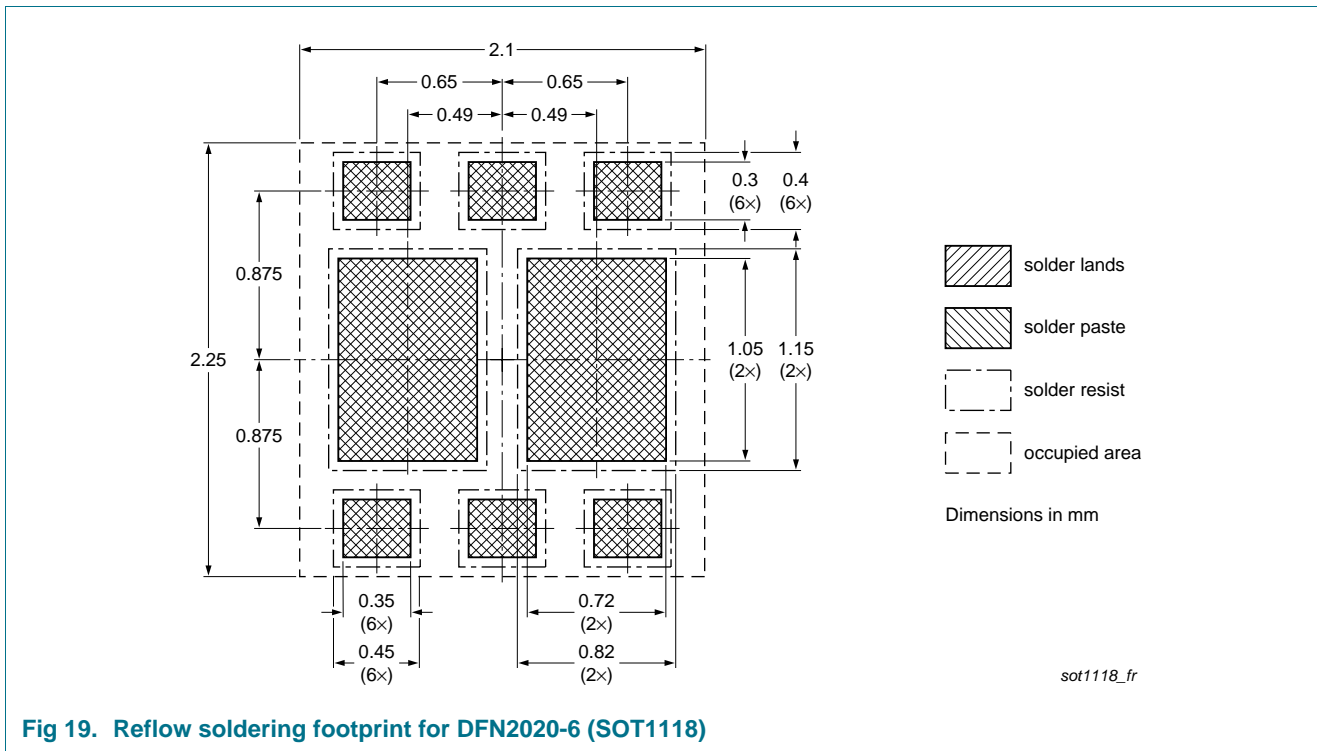


Fig 18. Package outline DFN2020-6 (SOT1118)

**10. Soldering**



**Fig 19. Reflow soldering footprint for DFN2020-6 (SOT1118)**



## 11. Revision history

**Table 8.** Revision history

| Document ID    | Release date | Data sheet status  | Change notice | Supersedes |
|----------------|--------------|--------------------|---------------|------------|
| PMDPB70XPE v.1 | 20120620     | Product data sheet | -             | -          |

## 12. Legal information

### 12.1 Data sheet status

| Document status <sup>[1]</sup> <sup>[2]</sup> | Product status <sup>[3]</sup> | Definition  |
|---|-------------------------------|---|
| Objective [short] data sheet                  | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet                | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet                    | Production                    | This document contains the product specification.                                     |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nexperia.com>.

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## 13. Contact information

For more information, please visit: <http://www.nexperia.com>

For sales office addresses, please send an email to: [salesaddresses@nexperia.com](mailto:salesaddresses@nexperia.com)

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